

07-10-2007



BT

Docket No.: 070679-0252

103425022

To the Director of the U. S. Patent and Trademark Office

and documents or the new address(es) below.

1. Name of Conveying Party(ies)  
Chun-Seok JEONG, Jae-Jin LEE  
Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)  
Name: HYNIX SEMICONDUCTOR INC.  
Internal Address:  
Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi,  
Kyoungki-do 467-860, REPUBLIC OF KOREA

3. Nature of Conveyance/Execution Date(s)  
Execution Date(s): June 26, 2007  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Joint Research Agreement  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other

Additional name(s) & address(es) attached?  Yes  No

4. Application or patent number(s):  
A. Patent Application No(s).

This document is being filed together with a new application  
B. Patent No(s).

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:  
Name: MCDERMOTT WILL & EMERY LLP  
Internal Address:  
Street Address: 600 13th Street, N.W.  
City: Washington State: D. C. Zip: 20005-3096  
Phone Number: 202.756.8000  
Fax Number: 202.756.8087  
Email Address:

6. Total number of applications and patents involved: 1  
7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00  
 Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

8. Payment Information:  
a. Credit Card Last 4 Numbers 500417  
Expiration Date  
b. Deposit Account Number 500417  
Authorized User Name

9. Signature. *Stephen A. Becker*  
Stephen A. Becker, 26,527

June 29, 2007

Name and Registration No. of Person Signing Signature  
Total number of pages including cover sheet, attachments and documents: 3

(SAB)

Docket No.: \_\_\_\_\_

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,  
**JEONG, Chun-Seok and LEE, Jae-Jin**

who has made a certain new and useful invention, hereby sells, assigns and transfers unto  
**Hynix Semiconductor Inc.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled  
**ON DIE THERMAL SENSOR HAVING ANALOG-TO-DIGITAL CONVERTER  
FOR USE IN SEMICONDUCTOR MEMORY DEVICE**

(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

*Chunseok Jeong*

June 26, 2007

Name: JEONG, Chun-Seok

INVENTOR

LEE JAE JIN

DATE SIGNED

June 26, 2007

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Name: LEE, Jae-Jin